

L Number	Hits	Search Text	DB	Time stamp
-	240	(bga adj package) and (bond adj wires) and (solder adj balls)	USPAT; US-PGPUB	2002/12/12 15:50
-	10	die adj down adj bga adj package	USPAT; US-PGPUB	2002/12/12 15:54
-	22	(die adj down) and (bga adj package)	USPAT; US-PGPUB	2002/12/12 15:56
-	80	(cavity adj down) and (bga adj package)	USPAT; US-PGPUB	2002/12/12 16:36
-	412	cavity adj down	USPAT; US-PGPUB	2002/12/12 16:47
-	0	6020637.pn. and stiffener	USPAT; US-PGPUB	2002/12/12 16:57
-	236	bga and stiffener	USPAT; US-PGPUB	2002/12/12 16:49
-	1	6020637.pn. and trace	USPAT; US-PGPUB	2002/12/12 18:30
-	0	tab adj shaped adj protruding adj edge	USPAT; US-PGPUB	2002/12/12 17:47
-	1	(tab adj shaped) and bga	USPAT; US-PGPUB	2002/12/12 17:49
-	530	protruding and bga	USPAT; US-PGPUB	2002/12/12 17:49
-	0	20020072214.pn. and (ground adj ring)	USPAT; US-PGPUB	2002/12/12 18:31
-	0	20020072214.pn. and (ground)	USPAT; US-PGPUB	2002/12/12 19:14
-	1	die adj attached adj stiffener	USPAT; US-PGPUB	2002/12/12 18:48
-	1	5843808.pn. and substrate	USPAT; US-PGPUB	2002/12/12 19:14

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